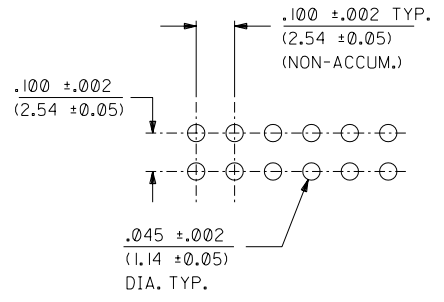
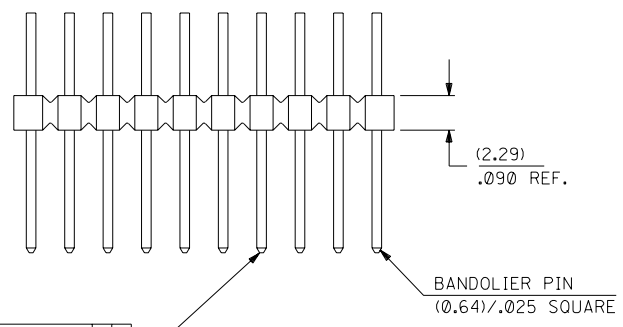
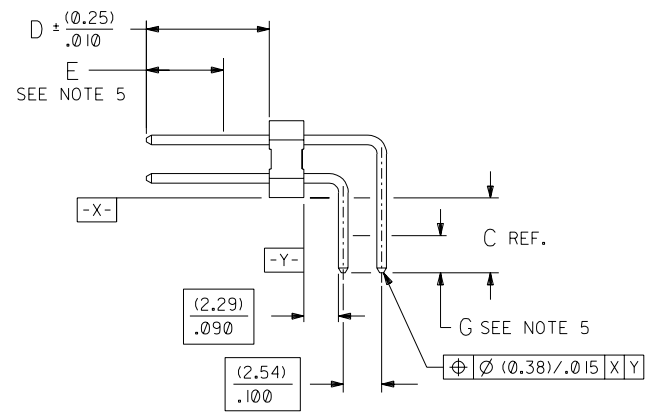
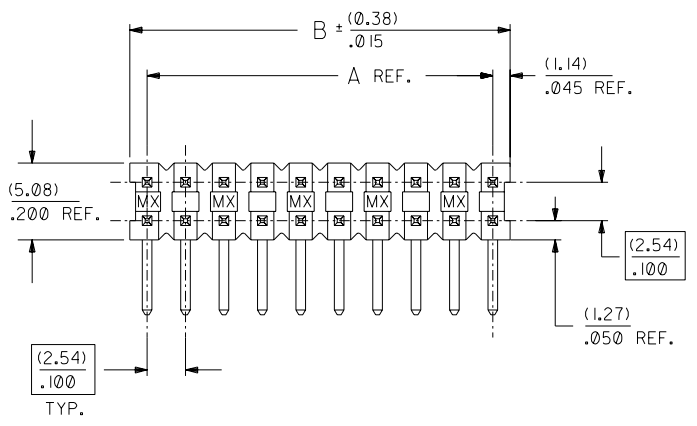


CKT. SIZE	DIM. A REF.		DIM. B REF.	
	(MM)	INCH	(MM)	INCH
4	(2.54)	.100	(4.83)	.190
6	(5.08)	.200	(7.37)	.290
8	(7.62)	.300	(9.91)	.390
10	(10.16)	.400	(12.45)	.490
12	(12.70)	.500	(14.99)	.590
14	(15.24)	.600	(17.53)	.690
16	(17.78)	.700	(20.07)	.790
18	(20.32)	.800	(22.61)	.890
20	(22.86)	.900	(25.15)	.990
22	(25.40)	1.000	(27.69)	1.090
24	(27.94)	1.100	(30.23)	1.190
26	(30.48)	1.200	(32.77)	1.290
28	(33.02)	1.300	(35.31)	1.390
30	(35.56)	1.400	(37.85)	1.490
32	(38.10)	1.500	(40.39)	1.590
34	(40.64)	1.600	(42.93)	1.690
36	(43.18)	1.700	(45.47)	1.790
38	(45.72)	1.800	(48.01)	1.890
40	(48.26)	1.900	(50.55)	1.990
42	(50.80)	2.000	(53.09)	2.090
44	(53.34)	2.100	(55.63)	2.190
46	(55.88)	2.200	(58.17)	2.290
48	(58.42)	2.300	(60.71)	2.390
50	(60.96)	2.400	(63.25)	2.490
52	(63.50)	2.500	(65.79)	2.590
54	(66.04)	2.600	(68.33)	2.690
56	(68.58)	2.700	(70.87)	2.790
58	(71.12)	2.800	(73.41)	2.890
60	(73.66)	2.900	(75.95)	2.990
62	(76.20)	3.000	(78.49)	3.090
64	(78.74)	3.100	(81.03)	3.190
66	(81.28)	3.200	(83.57)	3.290
68	(83.82)	3.300	(86.11)	3.390
70	(86.36)	3.400	(88.65)	3.490
72	(88.90)	3.500	(91.19)	3.590
74	(91.44)	3.600	(93.73)	3.690
76	(93.98)	3.700	(96.27)	3.790
78	(96.52)	3.800	(98.81)	3.890
80	(99.06)	3.900	(101.35)	3.990



RECOMMENDED P.C. BOARD HOLE LAYOUT



NOTES:

- PIN PUSHOUT FORCE: 4 LBS. MINIMUM
- FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
- PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE. (APPROX. .025 LNG X .006 WD. REF.) - 2 LOCATIONS
- WAFER TO BE FLAT WITHIN (0.03 MM/CM)/.003 IN./IN.
- MEASURE POINT FOR PLATING THICKNESS.
- THIS PRODUCT CONFORMS TO MOLEX PRODUCT SPEC. PS-70203.
- FOR ASSEMBLIES WITH VOIDS, REFER TO DRAWING NUMBER SDA-70203-5001-9999.
- PACKAGING INFORMATION: (UNLESS OTHERWISE NOTED IN TABLES)

CIRCUIT SIZE	PACKAGING DRAWING
4 THROUGH 8	PK-70873-0353
10 AND OVER	PK-70873-0075

FINISH:

- TIN - .000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
 - 15 GOLD - .000015 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - 30 GOLD - .000030 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
- *THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO ROHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

MATERIAL:

- WAFER - G.F. POLYESTER; 94V-0; COLOR: BLACK
- PIN - PHOSPHOR BRONZE

D	LEAD FREE UCP2004-1770 RWHITE 04/04/23
CI	REVISE PKGNG ECN UDT2000-0949 SCHAFFER 00/4/6
C	REVISED PER ECN # U60711 1/8/96 BJS/RCB
BI	ADDED EDP PER ECN # U60256 95/08/23 CAC
B	VOIDED EDP NO'S PER ECN # U60097 95/07/27 CAC
A	RELEASED PER ECN # U31656 11/18/93 REED

DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		▽ = 0 ▲ = 0		REVISE ONLY ON CAD SYSTEM	
INCH METRIC		TITLE		SALES ASSY-DUAL ROW WAFER W/BREAK-OFF OPTION RIGHT ANGLE/.025 SQ PINS	
3 PLACE ± .005	---	PART NO.		SDA-70203-0001-5000	
2 PLACE ± .01 ± 0.13	---	DRAWG. NO.		SEE CHART	
1 PLACE --- ± 0.25	---	FILE NAME		570203X1	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO.		1 OF 2	
DATE		DATE		11/18/93	
U.S.A.		U.S.A.			
MOLEX INCORPORATED		MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DA	
DRWG. BY: SMR	CHK'D BY: SMR	SCALE: 4: 1			

